

74AHC2G241; 74AHCT2G241

Dual buffer/line driver; 3-state

Rev. 3 — 13 May 2013

Product data sheet

1. General description

The 74AHC2G241; 74AHCT2G241 is a high-speed Si-gate CMOS device.

The 74AHC2G241; 74AHCT2G241 is a dual non-inverting buffer/line driver with 3-state outputs. The 3-state outputs are controlled by the output enable inputs $\overline{1OE}$ and $2OE$. A HIGH level at pin $\overline{1OE}$ causes output 1Y to assume a high-impedance OFF-state. A LOW level at pin $2OE$ causes output 2Y to assume a high-impedance OFF-state. Schmitt-trigger action at all inputs makes the circuit highly tolerant for slower input rise and fall times.

2. Features and benefits

- Symmetrical output impedance
- High noise immunity
- ESD protection:
 - ◆ HBM JESD22-A114E: exceeds 2000 V
 - ◆ MM JESD22-A115-A: exceeds 200 V
 - ◆ CDM JESD22-C101C: exceeds 1000 V
- Low power dissipation
- Balanced propagation delays
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Ordering information

Table 1. Ordering information

| Type number | Package | | | |
|-------------------------------|---|--------|--|----------|
| | Temperature range | Name | Description | Version |
| 74AHC2G241DP 74AHCT2G241DP | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | TSSOP8 | plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm | SOT505-2 |
| 74AHC2G241DC 74AHCT2G241DC | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | VSSOP8 | plastic very thin shrink small outline package; 8 leads; body width 2.3 mm | SOT765-1 |
| 74AHC2G241GD 74AHCT2G241GD | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | XSON8 | plastic extremely thin small outline package; no leads; 8 terminals; body $3 \times 2 \times 0.5$ mm | SOT996-2 |



4. Marking

Table 2. Marking

| Type number | Marking code ^[1] |
|---------------|-----------------------------|
| 74AHC2G241DP | A241 |
| 74AHCT2G241DP | C241 |
| 74AHC2G241DC | A41 |
| 74AHCT2G241DC | C41 |
| 74AHC2G241GD | A41 |
| 74AHCT2G241GD | C41 |

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

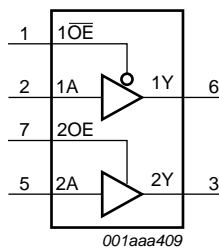


Fig 1. Logic symbol

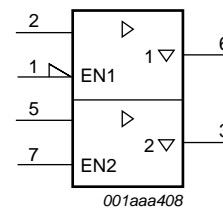


Fig 2. IEC logic symbol

6. Pinning information

6.1 Pinning

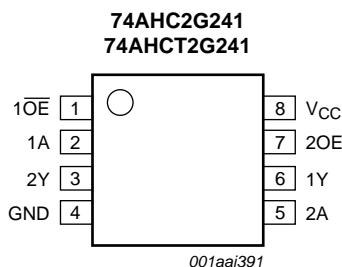


Fig 3. Pin configuration SOT505-2 (TSSOP8) and SOT765-1 (VSSOP8)

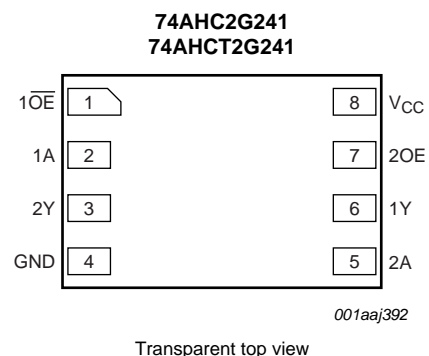


Fig 4. Pin configuration SOT996-2 (XSON8)

6.2 Pin description

Table 3. Pin description

| Symbol | Pin | Description |
|------------------|-----|-----------------------------------|
| $\overline{1OE}$ | 1 | output enable input (active LOW) |
| 1A | 2 | data input |
| 2Y | 3 | data output |
| GND | 4 | ground (0 V) |
| 2A | 5 | data input |
| 1Y | 6 | data output |
| 2OE | 7 | output enable input (active HIGH) |
| V_{CC} | 8 | supply voltage |

7. Functional description

Table 4. Function table^[1]

| Input | | Output | Input | | Output |
|------------------|----|--------|-------|----|--------|
| $\overline{1OE}$ | 1A | 1Y | 2OE | 2A | 2Y |
| L | L | L | H | L | L |
| L | H | H | H | H | H |
| H | X | Z | L | X | Z |

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|-------------------------|--|--------------------|------|------|
| V_{CC} | supply voltage | | -0.5 | +7.0 | V |
| V_I | input voltage | | -0.5 | +7.0 | V |
| I_{IK} | input clamping current | $V_I < -0.5$ V | ^[1] -20 | - | mA |
| I_{OK} | output clamping current | $V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V | ^[1] - | ±20 | mA |
| I_O | output current | -0.5 V < V_O < $V_{CC} + 0.5$ V | - | ±25 | mA |
| I_{CC} | supply current | | - | 75 | mA |
| I_{GND} | ground current | | -75 | - | mA |
| T_{stg} | storage temperature | | -65 | +150 | °C |
| P_{tot} | total power dissipation | $T_{amb} = -40$ °C to +125 °C | ^[2] - | 250 | mW |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP8 package: above 55 °C the value of P_{tot} derates linearly with 2.5 mW/K.
 For VSSOP8 package: above 110 °C the value of P_{tot} derates linearly with 8 mW/K.
 For XSON8 package: above 45 °C the value of P_{tot} derates linearly with 2.4 mW/K.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 74AHC2G241 | | | 74AHCT2G241 | | | Unit |
|------------------|-------------------------------------|---------------------------------|------------|-----|-----------------|-------------|-----|-----------------|------|
| | | | Min | Typ | Max | Min | Typ | Max | |
| V _{CC} | supply voltage | | 2.0 | 5.0 | 5.5 | 4.5 | 5.0 | 5.5 | V |
| V _I | input voltage | | 0 | - | 5.5 | 0 | - | 5.5 | V |
| V _O | output voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| T _{amb} | ambient temperature | | -40 | +25 | +125 | -40 | +25 | +125 | °C |
| Δt/ΔV | input transition rise and fall rate | V _{CC} = 3.3 V ± 0.3 V | - | - | 100 | - | - | - | ns/V |
| | | V _{CC} = 5.0 V ± 0.5 V | - | - | 20 | - | - | 20 | ns/V |

10. Static characteristics

Table 7. Static characteristics

Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|-------------------|---------------------------|--|-------|-----|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74AHC2G241 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 2.0 V | 1.5 | - | - | 1.5 | - | 1.5 | - | V |
| | | V _{CC} = 3.0 V | 2.1 | - | - | 2.1 | - | 2.1 | - | V |
| | | V _{CC} = 5.5 V | 3.85 | - | - | 3.85 | - | 3.85 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 2.0 V | - | - | 0.5 | - | 0.5 | - | 0.5 | V |
| | | V _{CC} = 3.0 V | - | - | 0.9 | - | 0.9 | - | 0.9 | V |
| | | V _{CC} = 5.5 V | - | - | 1.65 | - | 1.65 | - | 1.65 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = -50 μA; V _{CC} = 2.0 V | 1.9 | 2.0 | - | 1.9 | - | 1.9 | - | V |
| | | I _O = -50 μA; V _{CC} = 3.0 V | 2.9 | 3.0 | - | 2.9 | - | 2.9 | - | V |
| | | I _O = -50 μA; V _{CC} = 4.5 V | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -4.0 mA; V _{CC} = 3.0 V | 2.58 | - | - | 2.48 | - | 2.40 | - | V |
| | | I _O = -8.0 mA; V _{CC} = 4.5 V | 3.94 | - | - | 3.8 | - | 3.70 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = 50 μA; V _{CC} = 2.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 50 μA; V _{CC} = 3.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 50 μA; V _{CC} = 4.5 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 4.0 mA; V _{CC} = 3.0 V | - | - | 0.36 | - | 0.44 | - | 0.55 | V |
| | | I _O = 8.0 mA; V _{CC} = 4.5 V | - | - | 0.36 | - | 0.44 | - | 0.55 | V |
| I _{OZ} | OFF-state output current | V _I = V _{CC} or GND; V _{CC} = 5.5 V | - | - | 0.25 | - | 2.5 | - | 10 | μA |
| I _I | input leakage current | V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V | - | - | 0.1 | - | 1.0 | - | 2.0 | μA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 1.0 | - | 10 | - | 40 | μA |

Table 7. Static characteristics ...continued
 Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|--------------------|---------------------------|--|-------|-----|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| C _I | input capacitance | | - | 1.5 | 10 | - | 10 | - | 10 | pF |
| 74AHCT2G241 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 4.5 V to 5.5 V | 2.0 | - | - | 2.0 | - | 2.0 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 4.5 V to 5.5 V | - | - | 0.8 | - | 0.8 | - | 0.8 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = -50 μA | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -8.0 mA | 3.94 | - | - | 3.8 | - | 3.70 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = 50 μA | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 8.0 mA | - | - | 0.36 | - | 0.44 | - | 0.55 | V |
| I _{OZ} | OFF-state output current | V _I = V _{CC} or GND; V _{CC} = 5.5 V | - | - | 0.25 | - | 2.5 | - | 10 | μA |
| I _I | input leakage current | V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V | - | - | 0.1 | - | 1.0 | - | 2.0 | μA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 1.0 | - | 10 | - | 40 | μA |
| ΔI _{CC} | additional supply current | per input pin; V _I = 3.4 V; other inputs at V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 1.35 | - | 1.5 | - | 1.5 | mA |
| C _I | input capacitance | | - | 1.5 | 10 | - | 10 | - | 10 | pF |

11. Dynamic characteristics

Table 8. Dynamic characteristics
 GND = 0 V; for test circuit see [Figure 8](#).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|-------------------|-------------------|--|-------|-----|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74AHC2G241 | | | | | | | | | | |
| t _{pd} | propagation delay | nA to nY; see Figure 5 | | | | | | | | |
| | | V _{CC} = 3.0 V to 3.6 V | | | | | | | | |
| | | C _L = 15 pF | - | 4.7 | 8.0 | 1.0 | 9.5 | 1.0 | 11.5 | ns |
| | | C _L = 50 pF | - | 6.6 | 11.5 | 1.0 | 13.0 | 1.0 | 14.5 | ns |
| | | V _{CC} = 4.5 V to 5.5 V | | | | | | | | |
| | | C _L = 15 pF | - | 3.4 | 5.5 | 1.0 | 6.5 | 1.0 | 7.0 | ns |
| | | C _L = 50 pF | - | 4.7 | 7.5 | 1.0 | 8.5 | 1.0 | 9.5 | ns |

Table 8. Dynamic characteristics ...continued
GND = 0 V; for test circuit see Figure 8.

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|--------------------|-------------------------------|---|---------------------|-----|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| t _{en} | enable time | 1OE to 1Y; see Figure 6 [1] | | | | | | | | |
| | | V _{CC} = 3.0 V to 3.6 V [2] | | | | | | | | |
| | | C _L = 15 pF | - | 5.0 | 8.0 | 1.0 | 9.5 | 1.0 | 11.5 | ns |
| | | C _L = 50 pF | - | 6.9 | 11.5 | 1.0 | 13.0 | 1.0 | 14.5 | ns |
| | | V _{CC} = 4.5 V to 5.5 V [3] | | | | | | | | |
| | | C _L = 15 pF | - | 3.6 | 5.1 | 1.0 | 6.0 | 1.0 | 6.5 | ns |
| | | C _L = 50 pF | - | 4.9 | 7.5 | 1.0 | 8.5 | 1.0 | 9.5 | ns |
| | | 2OE to 2Y; see Figure 7 [1] | | | | | | | | |
| | | V _{CC} = 3.0 V to 3.6 V [2] | | | | | | | | |
| | | C _L = 15 pF | - | 4.9 | 8.0 | 1.0 | 9.5 | 1.0 | 10.0 | ns |
| | | C _L = 50 pF | - | 7.0 | 11.5 | 1.0 | 13.0 | 1.0 | 14.5 | ns |
| | | V _{CC} = 4.5 V to 5.5 V [3] | | | | | | | | |
| | | C _L = 15 pF | - | 3.6 | 5.6 | 1.0 | 6.3 | 1.0 | 7.0 | ns |
| | | C _L = 50 pF | - | 5.4 | 8.0 | 1.0 | 9.0 | 1.0 | 9.5 | ns |
| t _{dis} | disable time | 1OE to 1Y; see Figure 6 [1] | | | | | | | | |
| | | V _{CC} = 3.0 V to 3.6 V [2] | | | | | | | | |
| | | C _L = 15 pF | - | 6.0 | 9.7 | 1.0 | 11.5 | 1.0 | 12.5 | ns |
| | | C _L = 50 pF | - | 8.3 | 13.2 | 1.0 | 15.0 | 1.0 | 16.5 | ns |
| | | V _{CC} = 4.5 V to 5.5 V [3] | | | | | | | | |
| | | C _L = 15 pF | - | 4.1 | 6.8 | 1.0 | 8.0 | 1.0 | 8.5 | ns |
| | | C _L = 50 pF | - | 5.7 | 8.8 | 1.0 | 10.0 | 1.0 | 11.0 | ns |
| | | 2OE to 2Y; see Figure 7 [1] | | | | | | | | |
| | | V _{CC} = 3.0 V to 3.6 V [2] | | | | | | | | |
| | | C _L = 15 pF | - | 6.3 | 9.7 | 1.0 | 11.5 | 1.0 | 12.5 | ns |
| | | C _L = 50 pF | - | 9.0 | 13.2 | 1.0 | 15.0 | 1.0 | 16.5 | ns |
| | | V _{CC} = 4.5 V to 5.5 V [3] | | | | | | | | |
| | | C _L = 15 pF | - | 4.3 | 6.8 | 1.0 | 8.0 | 1.0 | 8.5 | ns |
| | | C _L = 50 pF | - | 6.1 | 8.8 | 1.0 | 10.0 | 1.0 | 11.0 | ns |
| C _{PD} | power dissipation capacitance | per buffer; C _L = 50 pF; f _i = 1 MHz; V _i = GND to V _{CC} | [4] | - | 10 | - | - | - | - | pF |
| 74AHCT2G241 | | | | | | | | | | |
| t _{pd} | propagation delay | nA to nY; see Figure 5 [1] | | | | | | | | |
| | | V _{CC} = 4.5 V to 5.5 V [3] | | | | | | | | |
| | | C _L = 15 pF | - | 3.4 | 5.5 | 1.0 | 6.5 | 1.0 | 7.0 | ns |
| | | C _L = 50 pF | - | 4.7 | 7.5 | 1.0 | 8.5 | 1.0 | 9.5 | ns |

Table 8. Dynamic characteristics ...continued
GND = 0 V; for test circuit see Figure 8.

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|------------------|-------------------------------|---|-------|-----|-----|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| t _{en} | enable time | 1OE to 1Y; see Figure 6 | [1] | | | | | | | |
| | | V _{CC} = 4.5 V to 5.5 V | [3] | | | | | | | |
| | | C _L = 15 pF | - | 3.9 | 5.1 | 1.0 | 6.0 | 1.0 | 6.5 | ns |
| | | C _L = 50 pF | - | 5.1 | 7.5 | 1.0 | 8.5 | 1.0 | 9.5 | ns |
| | | 2OE to 2Y; see Figure 7 | [1] | | | | | | | |
| | | V _{CC} = 4.5 V to 5.5 V | [3] | | | | | | | |
| t _{dis} | disable time | 1OE to 1Y; see Figure 6 | [1] | | | | | | | |
| | | V _{CC} = 4.5 V to 5.5 V | [3] | | | | | | | |
| | | C _L = 15 pF | - | 4.5 | 6.8 | 1.0 | 8.0 | 1.0 | 8.5 | ns |
| | | C _L = 50 pF | - | 6.1 | 8.8 | 1.0 | 10.0 | 1.0 | 11.0 | ns |
| | | 2OE to 2Y; see Figure 7 | [1] | | | | | | | |
| | | V _{CC} = 4.5 V to 5.5 V | [3] | | | | | | | |
| C _{PD} | power dissipation capacitance | per buffer; C _L = 50 pF; f _i = 1 MHz; V ₁ = GND to V _{CC} | [4] | - | 10 | - | - | - | - | pF |

- [1] t_{pd} is the same as t_{PLH} and t_{PHL}.
t_{en} is the same as t_{pZL} and t_{pZH}.
t_{dis} is the same as t_{pLZ} and t_{pHZ}.

[2] Typical values are measured at V_{CC} = 3.3 V.

[3] Typical values are measured at V_{CC} = 5.0 V.

[4] C_{PD} is used to determine the dynamic power dissipation P_D (μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

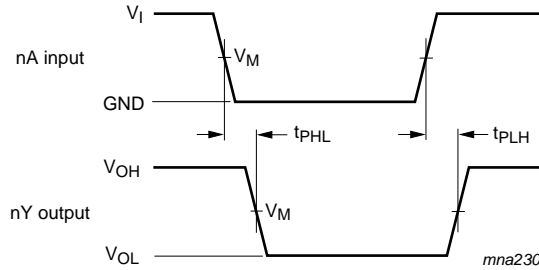
f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

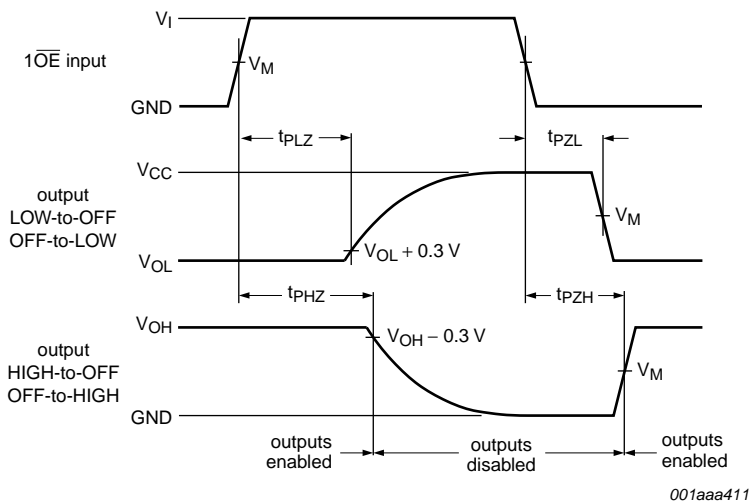
V_{CC} = supply voltage in Volts.

12. Waveforms



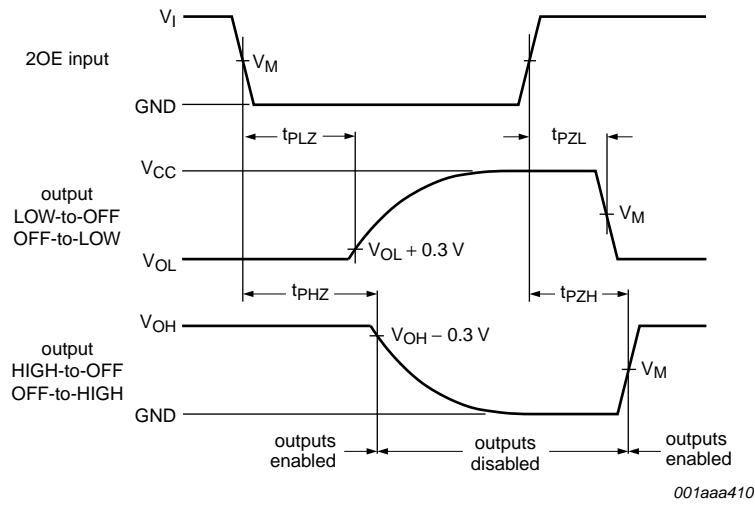
Measurement points are given in [Table 9](#).
 Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 5. The input (nA) to output (nY) propagation delays



Measurement points are given in [Table 9](#).
 Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 6. The input ($\overline{1OE}$) to output 1Y enable and disable times



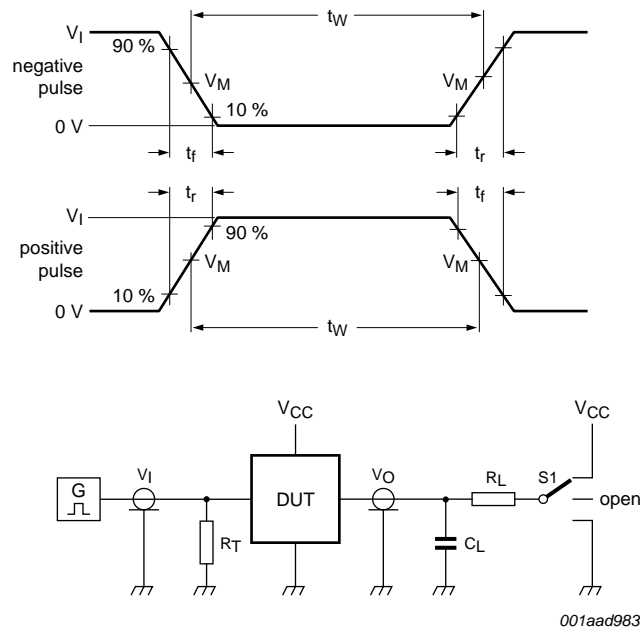
Measurement points are given in [Table 9](#).

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 7. The input (2OE) to output 2Y enable and disable times

Table 9. Measurement points

| Type | Input | Output |
|-------------|-------------|-------------|
| | V_M | V_M |
| 74AHC2G241 | $0.5V_{CC}$ | $0.5V_{CC}$ |
| 74AHCT2G241 | 1.5 V | $0.5V_{CC}$ |



Test data is given in [Table 10](#).

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistance.

S1 = Test selection switch.

Fig 8. Test circuit for measuring switching times

Table 10. Test data

| Type | Input | | Load | | S1 position | | |
|-------------|----------|-------------|--------------|--------------|--------------------|--------------------|--------------------|
| | V_I | t_r, t_f | C_L | R_L | t_{PHL}, t_{PLH} | t_{PZH}, t_{PHZ} | t_{PZL}, t_{PLZ} |
| 74AHC2G241 | V_{CC} | ≤ 3 ns | 15 pF, 50 pF | 1 k Ω | open | GND | V_{CC} |
| 74AHCT2G241 | 3 V | ≤ 3 ns | 15 pF, 50 pF | 1 k Ω | open | GND | V_{CC} |

13. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2

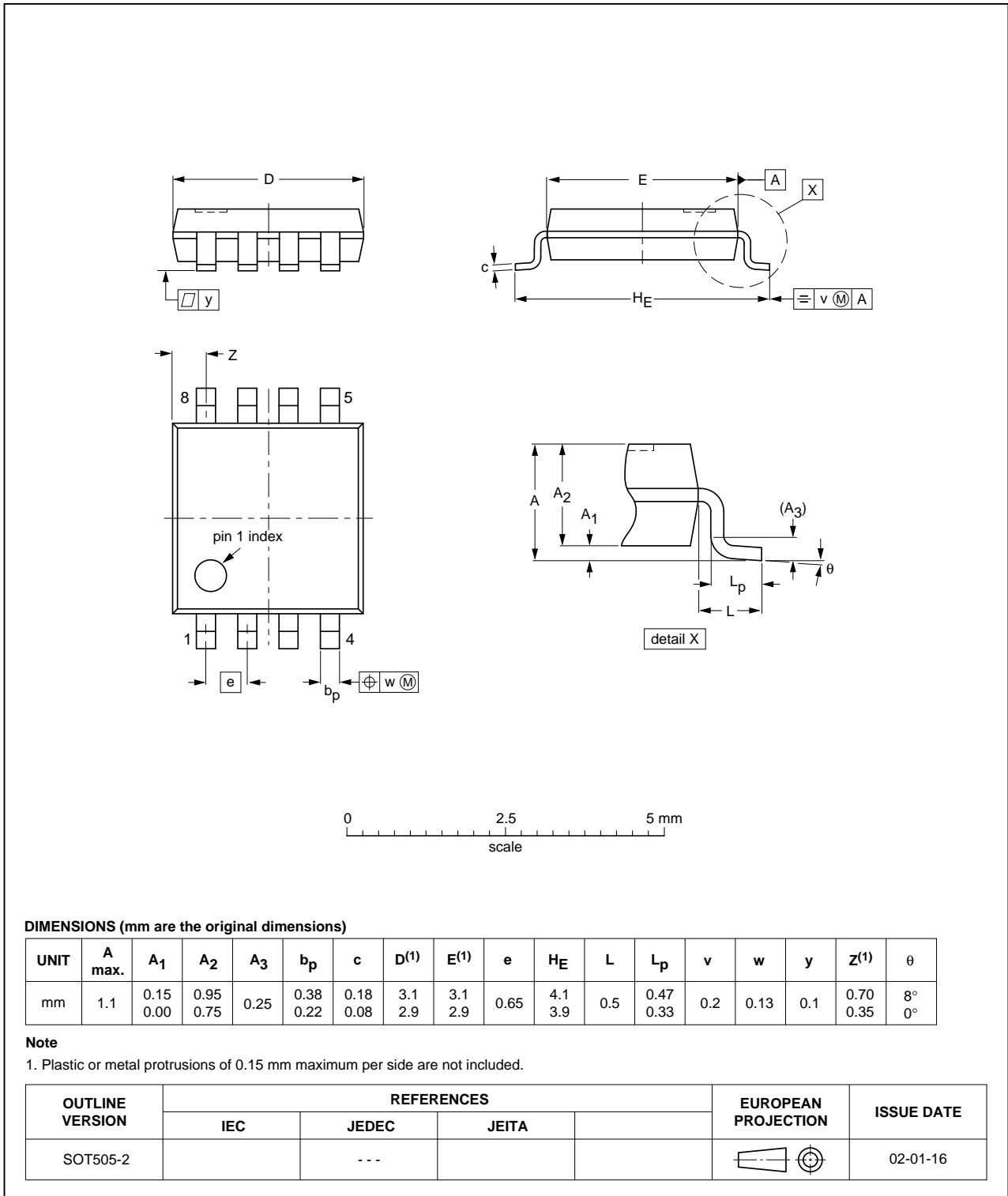


Fig 9. Package outline SOT505-2 (TSSOP8)

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1

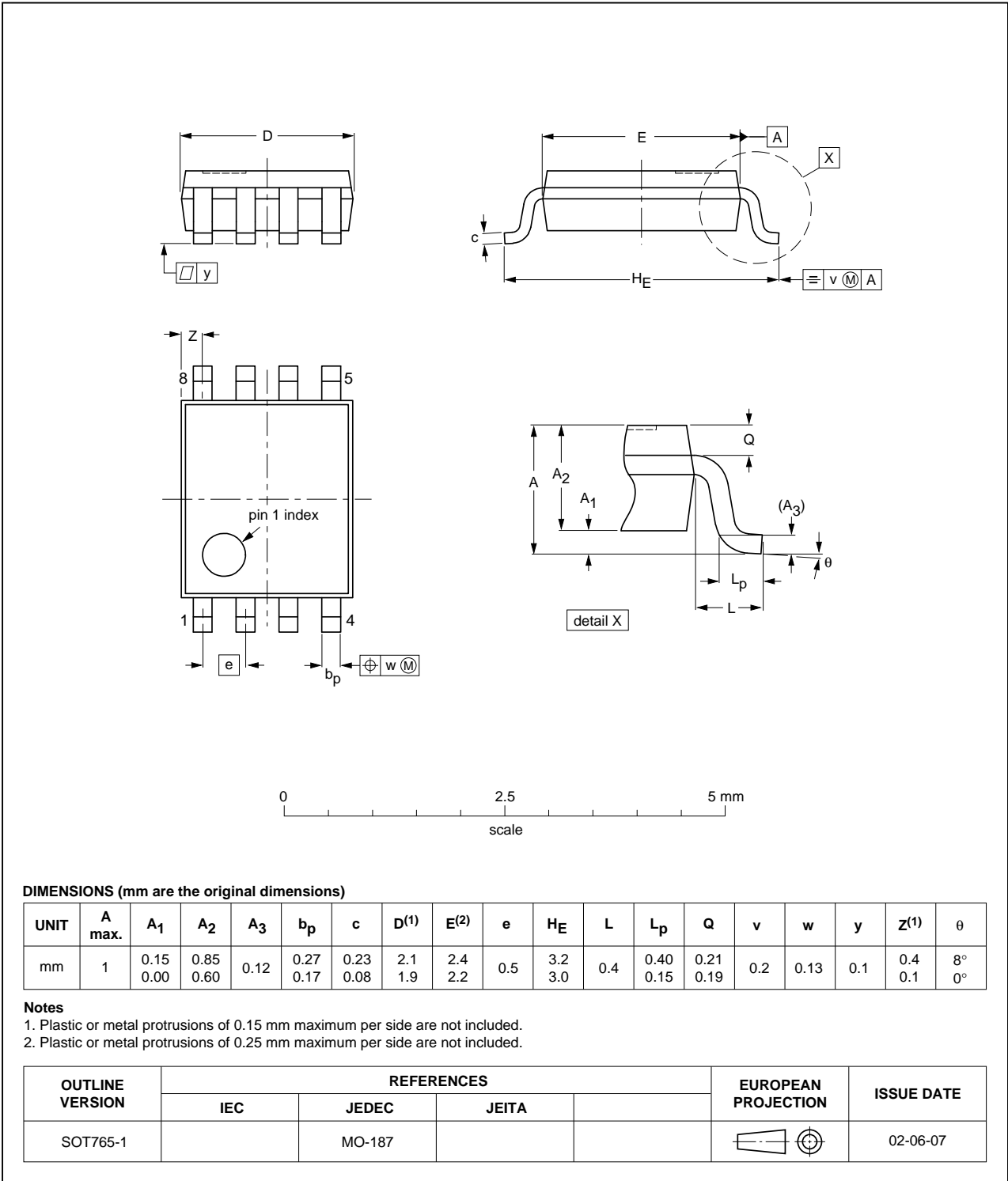


Fig 10. Package outline SOT765-1 (VSSOP8)

XSON8: plastic extremely thin small outline package; no leads;
8 terminals; body 3 x 2 x 0.5 mm

SOT996-2

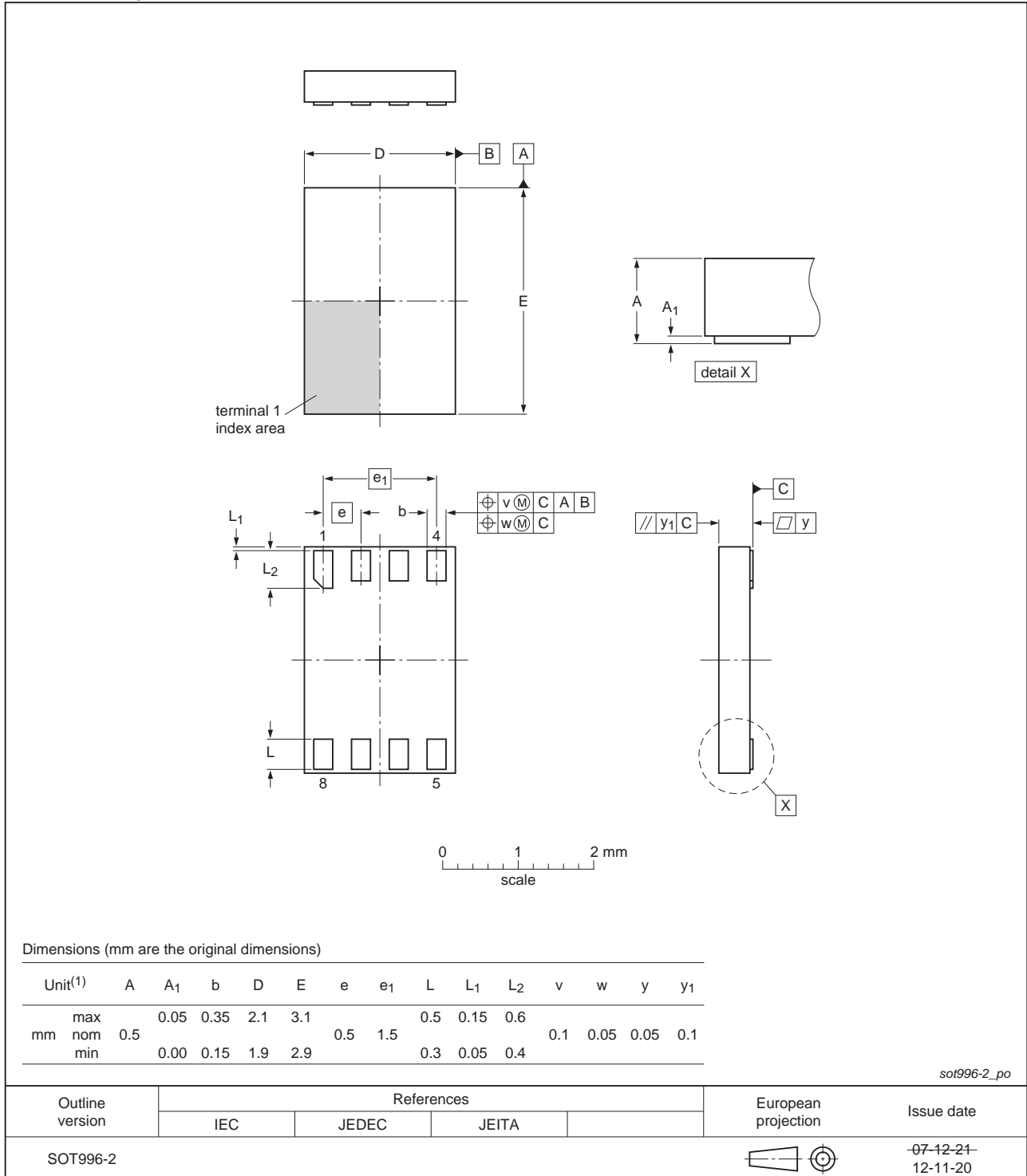


Fig 11. Package outline SOT996-2 (XSON8)

14. Revision history

Table 11. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|---------------------|---|--------------------|---------------|---------------------|
| 74AHC_AHCT2G241 v.3 | 20130513 | Product data sheet | - | 74AHC_AHCT2G241 v.2 |
| Modifications: | <ul style="list-style-type: none">For type number 74AHC2G241GD and 74AHCT2G241GD XSON8U has changed to XSON8. | | | |
| 74AHC_AHCT2G241 v.2 | 20090113 | Product data sheet | - | 74AHC_AHCT2G241 v.1 |
| Modifications: | <ul style="list-style-type: none">The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.Legal texts have been adapted to the new company name where appropriate.Added type number 74AHC2G241GD and 74AHCT2G241GD (XSON8U package). | | | |
| 74AHC_AHCT2G241 v.1 | 20040310 | Product data | - | - |

15. Legal information

15.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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